Silicon Carbide Schottky Diode

1200 V, 10 A

FFSB10120A-F085

Description

Silicon Carbide (SiC) Schottky Diodes use a completely new technology that provides superior switching performance and higher reliability compared to Silicon. No reverse recovery current, temperature independent switching characteristics, and excellent thermal performance sets Silicon Carbide as the next generation of power semiconductor. System benefits include highest efficiency, faster operating frequency, increased power density, reduced EMI, and reduced system size and cost.

Features

- Max Junction Temperature 175°C
- Avalanche Rated 100 mJ
- High Surge Current Capacity
- Positive Temperature Coefficient
- Ease of Paralleling
- No Reverse Recovery/No Forward Recovery
- AEC-Q101 qualified

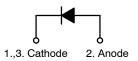
Applications

- Automotive HEV-EV Onboard Chargers
- Automotive HEV-EV DC-DC Converters

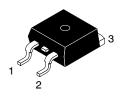


ON Semiconductor®

www.onsemi.com

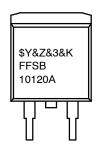


Schottky Diode



D²PAK2 (TO-263-2L) CASE 418BK

MARKING DIAGRAM



\$Y = ON Semiconductor Logo &Z = Assembly Plant Code = Numeric Date Code &3 = Lot Code

&K

FFSB10120A = Specific Device Code

ORDERING INFORMATION

See detailed ordering and shipping information on page 2 of this data sheet.

FFSB10120A-F085

ABSOLUTE MAXIMUM RATINGS (T_C = 25°C unless otherwise noted)

Symbol	Parameter		Ratings	Unit
V _{RRM}	Peak Repetitive Reverse Voltage		1200	V
E _{AS}	Single Pulse Avalanche Energy (Note 1)		100	mJ
I _F	Continuous Rectified Forward Current @ T _C < 164°C Continuous Rectified Forward Current @ T _C < 135°C		10	Α
			21	
I _{F, Max}	Non-Repetitive Peak Forward Surge Current	T _C = 25°C, 10 μs	850	Α
		T _C = 150°C, 10 μs	800	
I _{F, SM}	Non-Repetitive Forward Surge Current	Half-Sine Pulse, tp = 8.3 ms	90	Α
I _{F, RM}	Repetitive Forward Surge Current	Half-Sine Pulse, tp = 8.3 ms	35	Α
Ptot	Power Dissipation	T _C = 25°C	283	W
		T _C = 150°C	47	W
T _J , T _{STG}	Operating and Storage Temperature Range TO247 Mounting Torque, M3 Screw		-55 to +175	°C
			60	Ncm

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL CHARACTERISTICS

Symbol	Parameter	Ratings	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case, Max	0.53	°C/W

PACKAGE MARKING AND ORDERING INFORMATION

Part Number	Top Mark	Package	Shipping [†]
FFSB10120A-F085	FFSB10120A	D2PAK	800 Units/ Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

ELECTRICAL CHARACTERISTICS (T_C = 25°C unless otherwise noted)

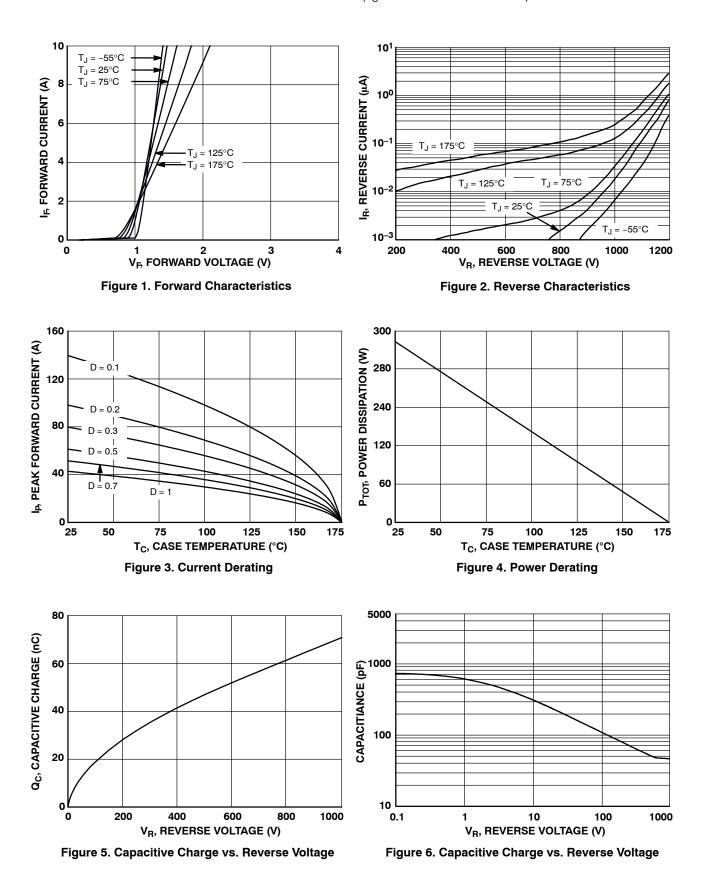
Symbol	Parameter	Test Conditions	Min	Тур.	Max.	Unit
V _F	Forward Voltage	I _F = 10 A, T _C = 25°C	-	1.45	1.75	V
		I _F = 10 A, T _C = 125°C	-	1.7	2	
		I _F = 10 A, T _C = 175°C	-	2	2.4	
I _R	Reverse Current	V _R = 1200 V, T _C = 25°C	-	-	200	μΑ
		V _R = 1200 V, T _C = 125°C	-	-	300	
		V _R = 1200 V, T _C = 175°C	-	-	400	
Q _C	Total Capacitive Charge	V = 800 V	-	62	-	nC
С	Total Capacitance	V _R = 1 V, f = 100 kHz	-	612	-	pF
		V _R = 400 V, f = 100 kHz	-	58	-	
		V _R = 800 V, f = 100 kHz	-	47	-	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

1. E_{AS} of 100 mJ is based on starting T_J = 25°C, L = 0.5 mH, I_{AS} = 20 A, V = 50 V.

FFSB10120A-F085

TYPICAL CHARACTERISTICS (T_C = 25°C unless otherwise noted)



FFSB10120A-F085

TYPICAL CHARACTERISTICS ($T_C = 25$ °C unless otherwise noted) (continued)

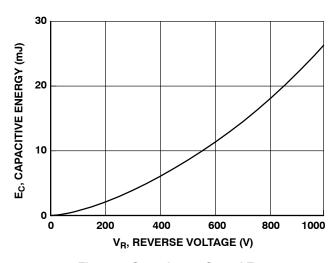


Figure 7. Capacitance Stored Energy

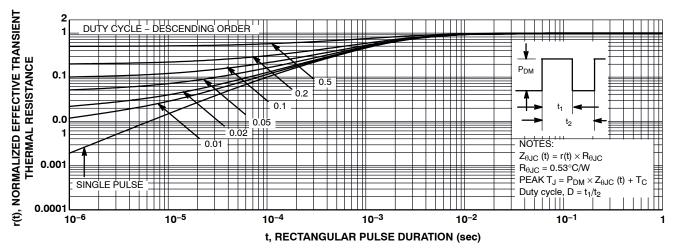


Figure 8. Junction-to-Case Transient Thermal Response Curve

TEST CIRCUIT AND WAVEFORMS

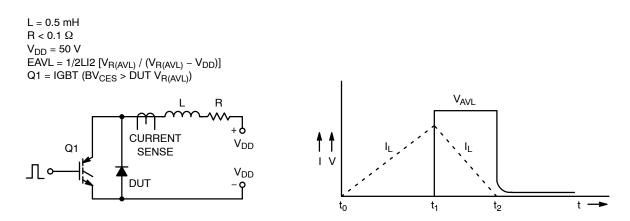
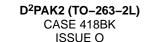
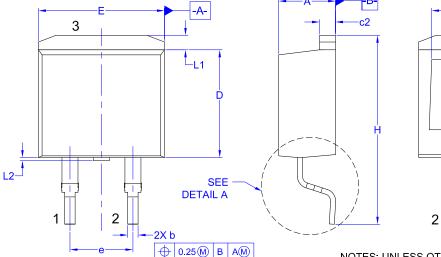
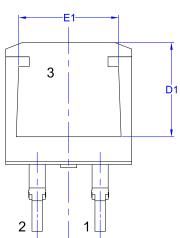


Figure 9. Unclamped Inductive Switching Test Circuit & Waveform



DATE 02 AUG 2018



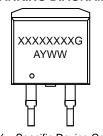


NOTES: UNLESS OTHERWISE SPECIFIED

- A) ALL DIMENSIONS ARE IN MILLIMETERS.
 B) REFERENCE JEDEC, TO-263, VARIATION AB.
- C) DIMENSIONING AND TOLERANCING PER
 DIMENSIONING AND TOLERANCING PER
- ASME Y14.5 2009.
 D) LANDPATTERN RECOMMENDATION PER IPC
- D) LANDPATTERN RECOMMENDATION PER IPO TO254P1524X482-3N

DETAIL A, ROTATED 90°	B)
SCALE: 2X	'(
GAUGE PLANE	D)
M	L3
B 0.10 SEATING —	-A1
GENERIC PLANE	—10.67—— -

GENERIC
MARKING DIAGRAM*



XXX = Specific Device Code

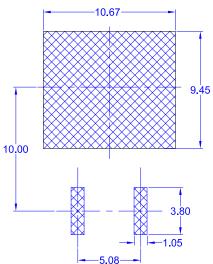
A = Assembly Location

Y = Year

WW = Work Week

G = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb–Free indicator, "G" or microdot " ■", may or may not be present. Some products may not follow the Generic Marking.



LAND PATTERN RECOMMENDATION
UNLESS NOTED. ALL DIMS TYPICAL

MIN	NOM	MAX	
4.06	4.57	4.83	
0.00	0.10	0.25	
0.51	0.81	0.99	
0.30	0.407	0.74	
1.14	1.30	1.65	
8.38	8.69	9.65	
7.30	7.80	8.30	
9.65	10.16	10.67	
8.00	8.62	9.00	
5.08 BSC			
14.60	15.35	15.88	
1.78	2.54	2.79	
0.90	1.29	1.68	
0.00	0.15	0.25	
0.25 BSC			
0°	4° 8°		
	4.06 0.00 0.51 0.30 1.14 8.38 7.30 9.65 8.00 14.60 1.78 0.90 0.00	4.06 4.57 0.00 0.10 0.51 0.81 0.30 0.407 1.14 1.30 8.38 8.69 7.30 7.80 9.65 10.16 8.00 8.62 5.08 BS 14.60 15.35 1.78 2.54 0.90 1.29 0.00 0.15 0.25 BS	

MILLIMETERS

DOCUMENT NUMBER:	98AON93788G	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.		
DESCRIPTION:	D ² PAK2 (TO-263-2L)		PAGE 1 OF 1	

ON Semiconductor and are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. ON Semiconductor does not convey any license under its patent rights nor the rights of others.

onsemi, ONSEMI, and other names, marks, and brands are registered and/or common law trademarks of Semiconductor Components Industries, LLC dba "onsemi" or its affiliates and/or subsidiaries in the United States and/or other countries. onsemi owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of onsemi's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. Onsemi reserves the right to make changes at any time to any products or information herein, without notice. The information herein is provided "as-is" and onsemi makes no warranty, representation or guarantee regarding the accuracy of the information, product features, availability, functionality, or suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using onsemi products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications provided by onsemi. "Typical" parameters which may be provided in onsemi data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. onsemi does not convey any license under any of its intellectual property rights nor the rights of others. onsemi products are not designed, intended, or authorized for use as a critical component in life support systems or any EDA class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer pu

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT: Email Requests to: orderlit@onsemi.com

onsemi Website: www.onsemi.com

TECHNICAL SUPPORT North American Technical Support: Voice Mail: 1 800-282-9855 Toll Free USA/Canada Phone: 011 421 33 790 2910

Europe, Middle East and Africa Technical Support:

Phone: 00421 33 790 2910

For additional information, please contact your local Sales Representative

X-ON Electronics

Largest Supplier of Electrical and Electronic Components

Click to view similar products for Schottky Diodes & Rectifiers category:

Click to view products by ON Semiconductor manufacturer:

Other Similar products are found below:

MA4E2039 D1FH3-5063 MBR0530L-TP MBR10100CT-BP MBR1545CT MMBD301M3T5G RB160M-50TR RB551V-30

BAS16E6433HTMA1 BAT 54-02LRH E6327 NSR05F40QNXT5G NTE555 JANS1N6640 SB07-03C-TB-H SB1003M3-TL-W SK310-T

SK32A-LTP SK34B-TP SS3003CH-TL-E GA01SHT18 CRS10I30A(TE85L,QM MA4E2501L-1290 MBRB30H30CT-1G SB007-03C-TB-E SK32A-TP SK33B-TP SK38B-TP NRVBM120LT1G NTE505 NTSB30U100CT-1G SS15E-TP VS-6CWQ10FNHM3 ACDBA1100LR-HF ACDBA1200-HF ACDBA2100-HF ACDBA3100-HF CDBQC0530L-HF ACDBA340-HF ACDBA260LR-HF

ACDBA1100-HF SK310B-TP MA4E2502L-1246 MA4E2502H-1246 NRVBM120ET1G NSR01L30MXT5G NTE573 NTE6081 SB560 PMAD1108-LF